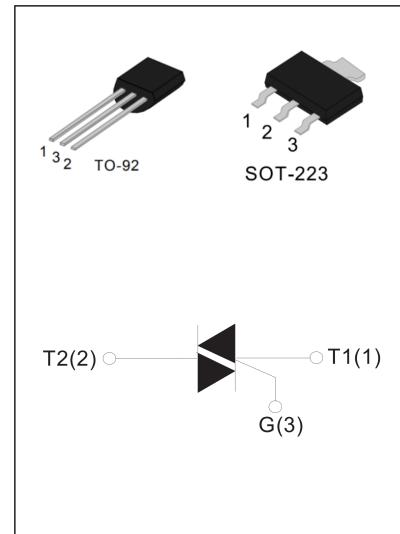


MAIN FEATURES

Symbol	Value	Unit
I _{T(RMS)}	1	A
V _{DRM} V _{RRM}	800	V
V _{TM}	1.55	V



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T _{STG}	-40 ~ 150	°C
Operating junction temperature range	T _J	-40~125	°C
Repetitive peak off-state voltage (T = 25°C)	V _{DRM}	800	V
Repetitive peak reverse voltage (T = 25°C)	V _{RRM}	800	V
Non repetitive surge peak Off-state voltage	V _{DSDM}	V _{DRM} + 100	V
Non repetitive peak reverse voltage	V _{RSM}	V _{RRM} + 100	V
TO-92 T _c = 50°C SOT-223 T _c = 65°C	I _{T(RMS)}	1	A
Non repetitive surge peak on-state current (full cycle, F=50Hz)	I _{TSM}	12.5	A
I ² t value for fusing (tp=10ms)	I ² t	0.78	A ² s
Critical rate of rise of on-state current (I = 2×IGT)	dI/dt	20	A/μs
Peak gate current	I _{GM}	1	A
Average gate power dissipation	P _{G(AV)}	0.1	W

ELECTRICAL CHARACTERISTICS (T=25 °C unless otherwise specified)
3 Quadrants

Symbol	Test Condition	Quadrant		Value		Unit
				SW	TW	
I _{GT}	V = 12V R = 33Ω	I II III	MAX.	5	10	mA
V _{GT}		I II III	MAX.	1.3	1.3	V
V _{GD}	V _D =V _{DRM} T _j =125°C R=3.3KΩ	I II III	MIN.	0.2	0.2	V
I _L	I _G =1.2I _{GT}	I II III	MAX.	15	30	mA
I _H	I _T =100mA		MAX.	10	25	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125°C		MIN.	20	50	V/μs
(dV/dt)c	Without snubber T _j =125°C		MIN.	-	-	V/μs

4 Quadrants

Symbol	Test Condition	Quadrant		Value		Unit
				D	E	
I _{GT}	V = 12V R = 33Ω	I II III	MAX.	5	10	mA
		IV		10	25	
V _{GT}	I II III IV		MAX.	1.3	1.3	V
V _{GD}	V _D =V _{DRM} T _j =125°C R=3.3KΩ	I II III IV	MIN.	0.2	0.2	V
I _L	I _G =1.2I _{GT}	I III IV	MAX.	15	20	mA
		II		20	25	
I _H	IT=100mA		MAX.	10	15	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125°C		MIN.	20	50	V/μs
(dV/dt)c	Without snubber T _j =125°C		MIN.	-	-	V/μs

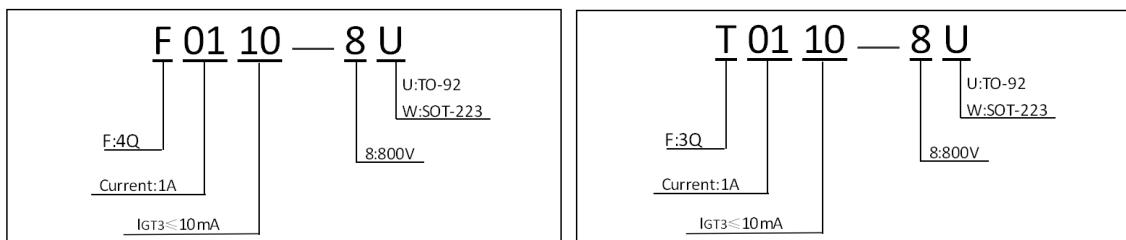
STATIC CHARACTERISTICS

Symbol	Parameter		Value	Unit
V _{TM}	I _{TM} =1.4A t _p =380μs	T _j =25°C	1.55	V
I _{DRM}	V _D =V _{DRM} V _R =V _{RRM}	T _j =25°C	5	μA
I _{RRM}		T _j =125°C	0.5	mA

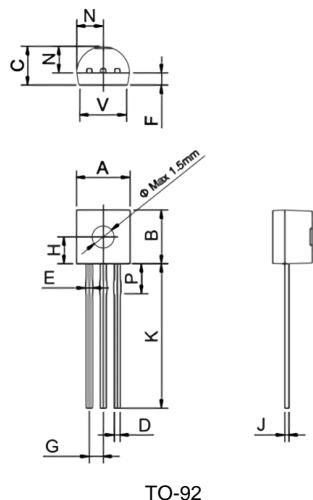
Thermal Resistances

Symbol	Parameter	Value	Unit
Rth(j-a)	junction to ambient	SOT-223	60
		TO-92	150
Rth(j-c)	Junction to tab (AC)	SOT-223	25
	Junction to lead (AC)	TO-92	60

Ordering Information Scheme

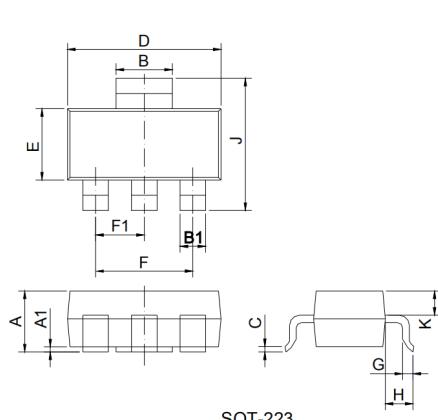


Package Mechanical Data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.45		5.20	0.175		0.205
B	4.32		5.33	0.170		0.210
C	3.18		4.19	0.125		0.165
D	0.254		0.506	0.016		0.021
E	0.30		0.70	0.024		0.031
F	-	1.30	-	-	0.051	-
G	-	1.27	-	-	0.050	-
H	-	2.30	-	-	0.091	-
J	0.30		0.50	0.011		0.020
K	12.70		15.0	0.500		0.591
N	2.04		2.66	0.080		0.105
P	1.86		2.06	0.073		0.081
V	-		4.50	-		0.169

Package Mechanical Data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.5	1.6	1.8	0.059	0.063	0.071
A1	0.01	0.06	0.10	0.001	0.002	0.004
B	2.9	3.0	3.1	0.114	0.118	0.122
B1	0.6	0.7	0.8	0.024	0.028	0.031
C	0.22	0.26	0.32	0.009	0.010	0.013
D	6.3	6.5	6.7	0.248	0.256	0.264
E	3.3	3.5	3.7	0.130	0.138	0.146
F		4.6			0.181	
F1		2.3			0.091	
G	0.7	0.9	1.1	0.028	0.035	0.043
H	1.5	1.75	2	0.059	0.069	0.079
J	6.7	7.0	7.3	0.264	0.276	0.287
K		0.9			0.035	

FIG.1:Maximum power dissipation versus RMS on-state current(full cycle)

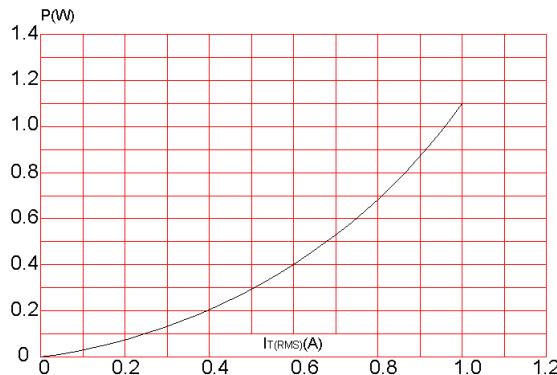


FIG.2:RMS on-state current versus mounting base temperature(full cycle)

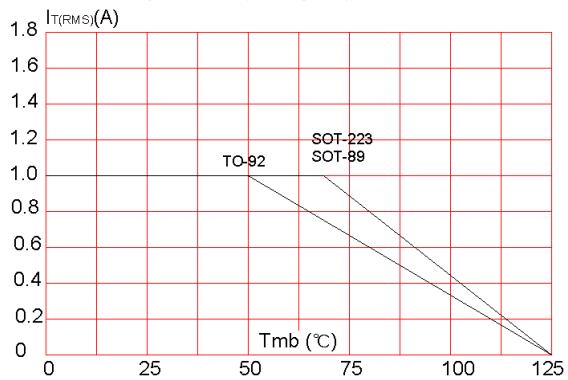


FIG.3:On-state characteristics (maximum values).

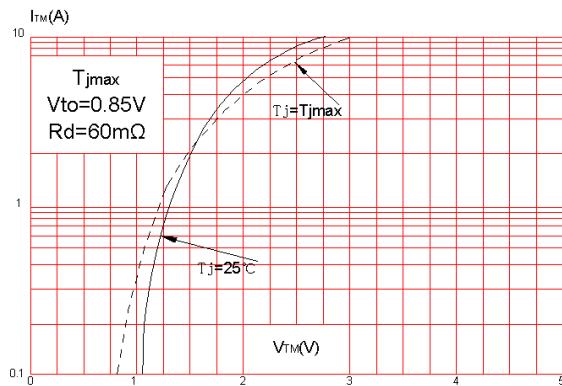


FIG.4:Surge peak on-state current versus number of cycles.

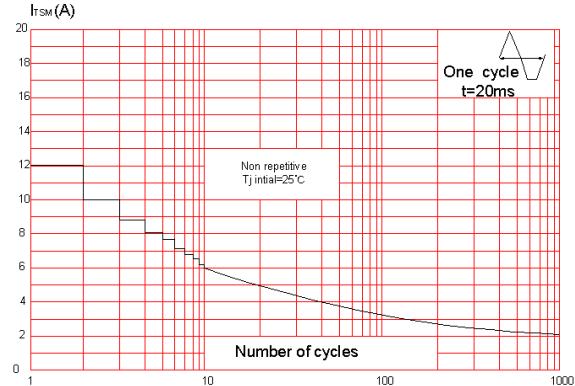


FIG.5:Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$,and corresponding value of I^2t .

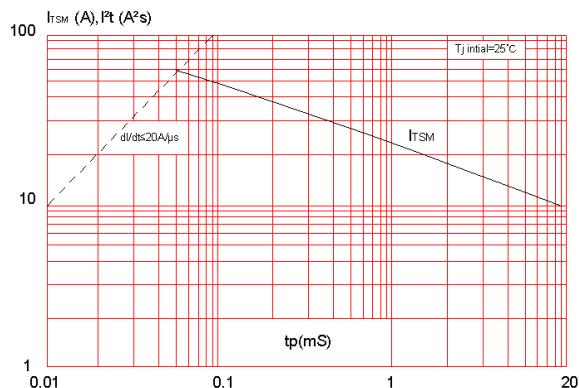


FIG.6:Relative variations of gate trigger current,holding current and latching current versus junction temperature(typical values)

